

01-14-2004



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**PATENTS ONLY**

U.S. DEPARTMENT OF COMMERCE  
U.S. Patent and Trademark Office

31353 U.S. PTO  
10/751941  
010704

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Sungkwon C. Hong

1.7.04

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date: December 16, 2003

2. Name and address of receiving party(ies)

Name: MICRON TECHNOLOGY, INC.

Internal Address:

Street Address:

Micron Technology, Inc.  
8000 S. Federal Way

City: Boise

State: ID Zip: 83707-0006

Additional name(s) & address(es) attached: ☐ Yes ☒ No

4. Application number(s) or patent number(s):

10751941

If this document is being filed together with a new application, the execution date of the new application is:

A. Patent Application No.(s):

This application

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Thomas J. D'Amico

DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP

Internal Address: Atty. Dkt.: M4065.0964/P964

Street Address:  
2101 L Street NW

City:  
Washington

State: DC Zip: 20037-1526

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41)

\$ 40.00

☐ Enclosed

☐ Authorized to be charged to deposit account

☒ Authorized to be charged to credit card  
(Form 2038 enclosed)

8. Deposit account number:

04-1073

(Attach duplicate copy of this page if paying by deposit account)

**DO NOT USE THIS SPACE**

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Thomas J. D'Amico  
Name of Person Signing

Signature

January 7, 2004  
Date

Total number of pages including cover sheet, attachments, and documents:

## ASSIGNMENT AND AGREEMENT

For value received, I, Sungkwon C. Hong, hereby sell, assign and transfer to Micron Technology, Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled METHODS AND APPARATUS WITH SILICIDE ON CONDUCTIVE STRUCTURES, described in an application for Letters Patent of the United States, executed by me of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

I request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

I agree that, when requested, I shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

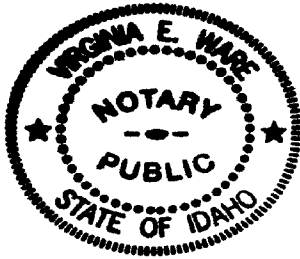
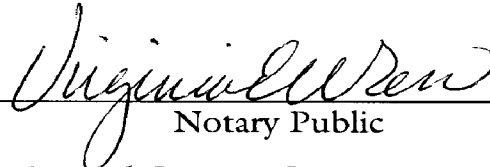


Sungkwon C. Hong

Date: Dec. 16, 2003

United States of America )  
 State of Idaho ) ss.:  
 County of Ada )

On this 16<sup>th</sup> day of December, 2003, before me personally came Sungkwon C. Hong, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same.

Notary Public

Exp. 08-01-07